



Challenges of AI Testing
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New Processors and ASICs are being developed to meet the need of new Artificial Intelligence (AI) markets, for both server and end-user applications. These devices, especially those for server applications, will bring new challenges such as very high power consumption, very high pin count probe, new device bring-up challenges, and new high speed serial scan requirements with the IEEE1149.10 standard. This presentation will explore these challenges and solutions under development for them.